AUG 0 3 2004 &

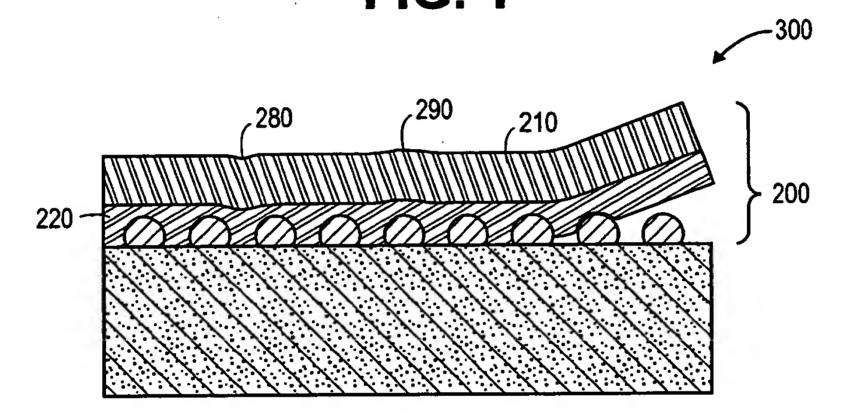
(503) 439-8778 Blakely, Sokoloff, Taylor & Zafman LLP Title: Multi-Purpose Planarizing/Back-Grind/Pre-Underfill

Arrangements for Bumped Wafers and Die 1st Named Inventor: Takashi Kumamoto

Application No.: 09/893,588 Sheet: 1 of 5

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130 120 110 45 FIG. 1



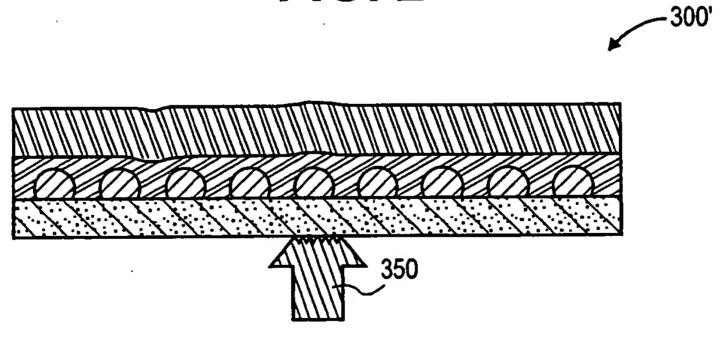
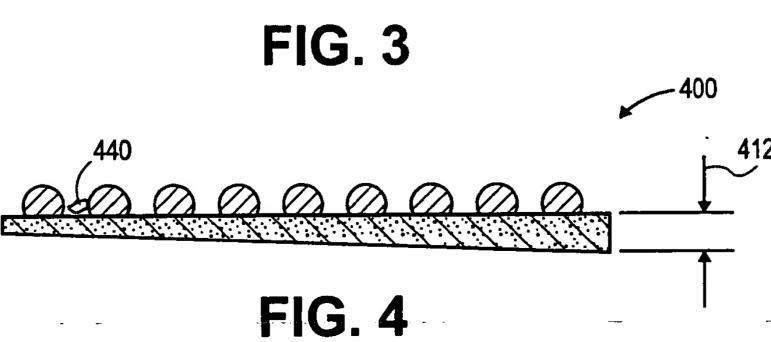


FIG. 2





(503) 439-8778 Blakely, Sokoloff, Taylor & Zafman LLP

Title: Multi-Purpose Planarizing/Back-Grind/Pre-Underfill
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1st Named Inventor: Takashi Kumamoto

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FIG. 5A

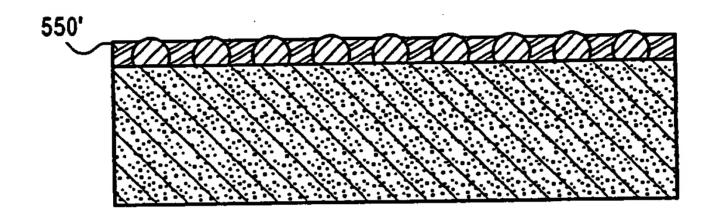


FIG. 5B

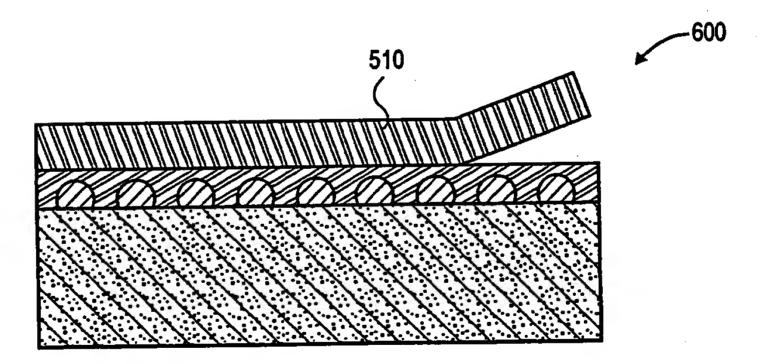


FIG. 6

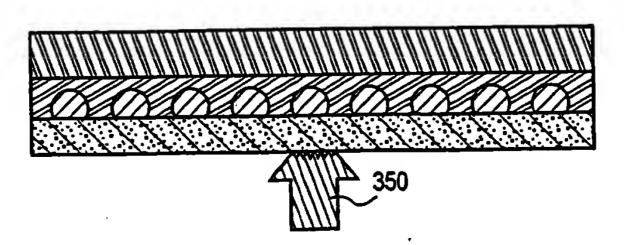


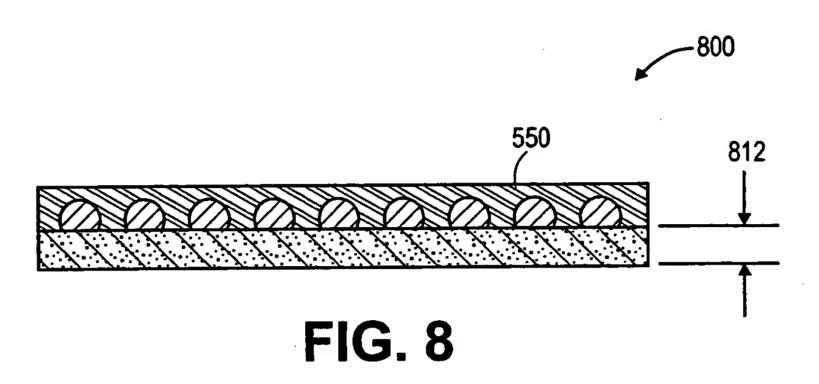
FIG. 7



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Docket No.: 42390P12093.



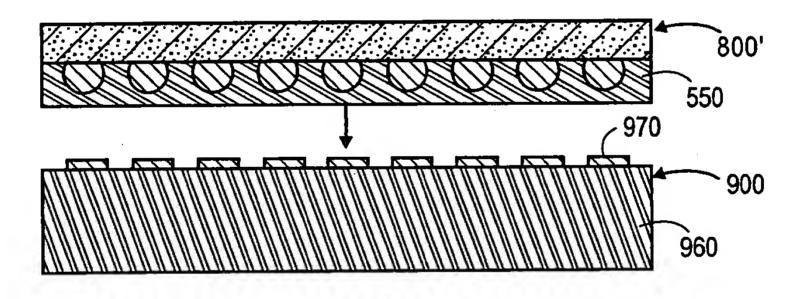
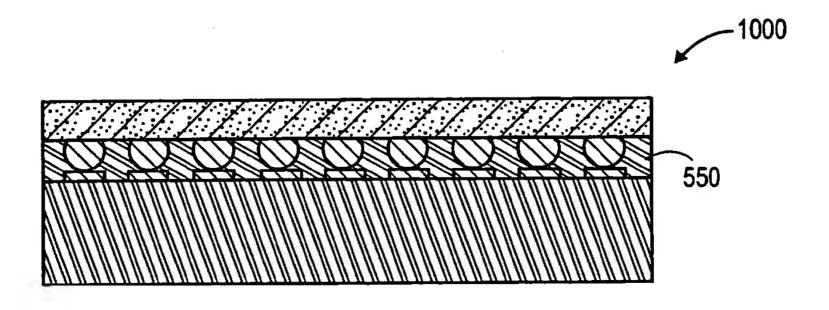


FIG. 9



**FIG. 10** 



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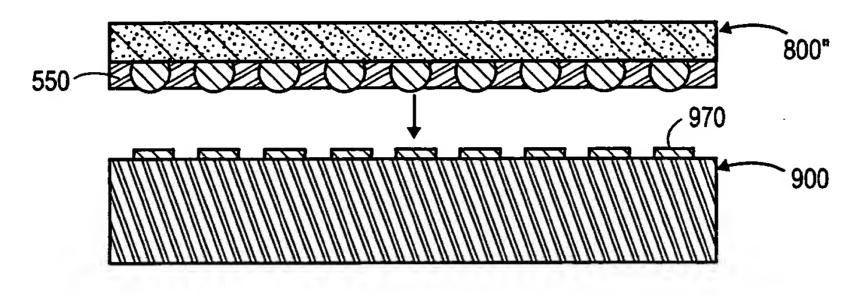
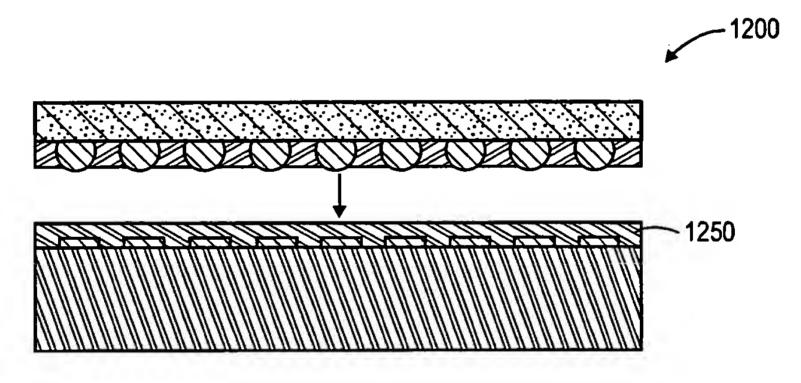


FIG. 11



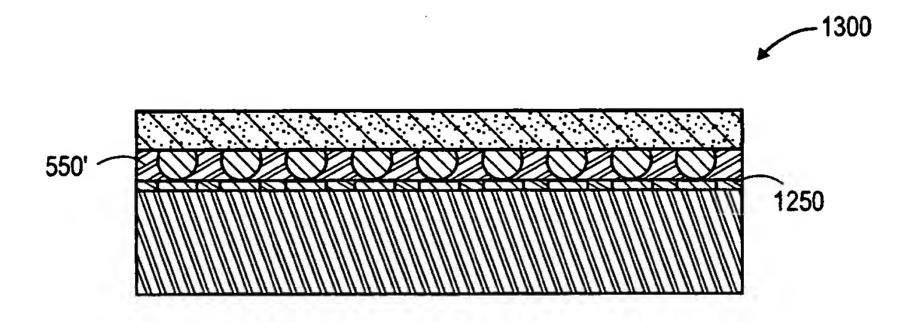


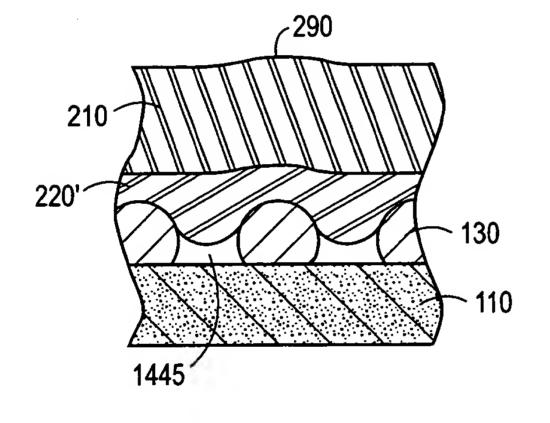
FIG. 13

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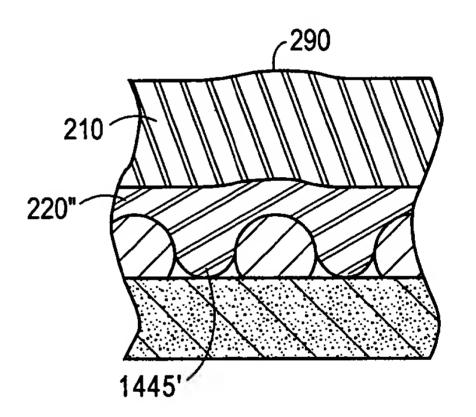


FIG. 14

**FIG. 15**